



## ESD3.3V02D-ULC

#### Description

Feature

The ESD3.3V02D-ULC is ultra low capacitance TVS arrays designed to protect high speed data interfaces. This series has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from over-voltage caused by ESD (electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients).



## **Functional Diagram**

**Mechanical Data** 

JEDEC 0201/DFN0603 Package

Weight 0.3 Milligrams(Approximate)

Mounting position: Any

Polarity: Color band denotes cathode end.

Molding Compound Flammability Rating : UL 94V-O

- Ultra small SMD package
- Ultra-Low capacitance
- Protects One Bidirectional I/O line
- Low clamping voltage
- Working voltages :3.3V
- Low leakage current
- ◆ IEC61000-4-2(ESD):±25kV (air discharge)
  - ±20kV (contact discharge);

#### Applications

- USB 3.0 / USB 3.1 Interfaces
- HDMI 1.4 / HDMI 2.0 Interfaces
- Video Graphics Cards
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Industrial Controls
- Peripherals

#### **Mechanical Characteristics**

Symbol	Parameter	Value	Units		
P <sub>PP</sub>	Peak Pulse Power (tp=8/20µs waveform)	96	Watts		
ΤL	Lead Soldering Temperature	260 (10 sec.)	°C		
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C		
TJ	Operating Junction Temperature Range	-40 to +125	°C		

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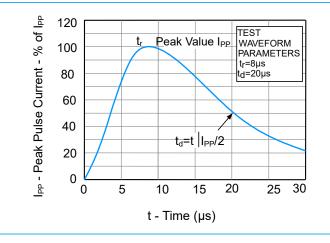


## ESD3.3V02D-ULC

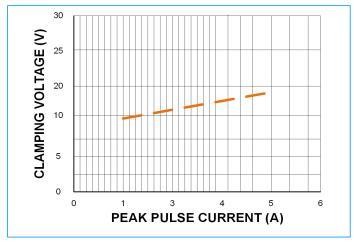
Electrical Characteristics (@ 25°C Unless Otherwise Specified )						
Characteristics	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Reverse Working Voltage	V <sub>RWM</sub>				3.3	V
Reverse Breakdown Voltage	$V_{BR}$	I <sub>T</sub> =1mA;	4.5	-	ł	V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> =3.3V, T=25°C;			1	μA
Positive Clamping Voltage	Vc	I <sub>PP</sub> =4.8A, T <sub>P</sub> =8/20μs;			20	V
TLP Clamping Voltage	V <sub>CL</sub>	I <sub>PP</sub> =16A, T <sub>P</sub> =100ns;		19.6		V
Junction capacitance	CJ	V <sub>R</sub> = 0V, f = 1MHz;			0.25	pF

### **Characteristic Curves**

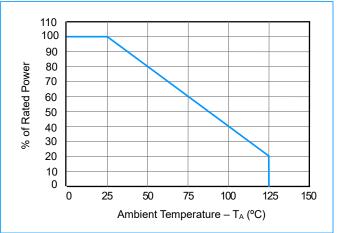
#### Fig1. 8/20µs Pulse Waveform

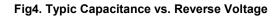


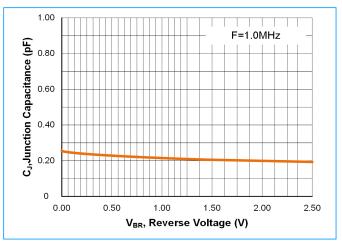
### Fig3. Clamping Voltage vs. Peak Pulse Current



#### Fig2. Power Rating Derating Curve







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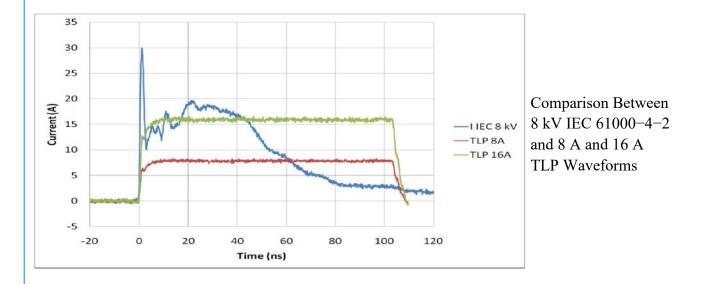




## ESD3.3V02D-ULC

#### Transmission Line Pulse (TLP)

Transmission Line Pulse (TLP) is a measurement technique used in the Electrostatic Discharge (ESD) arena to characterize performance attributes of devices under ESD stresses. TLP is able to obtain current versus voltage (I–V) curves in which each data point is obtained with a 100 ns long pulse, with currents up to 40 A. TLP was first used in the ESD field to study human body model (HBM) in integrated circuits, but it is an equally valid tool in the field of system level ESD. The applicability of TLP to system level ESD is illustrated in Figure 1, which compares an 8 KV IEC 61000–4–2 current waveform with TLP current pulses of 8 and 16 A. The current levels and time duration for the pulses are similar and the initial rise time for the TLP pulse is comparable to the rise time of the IEC 61000–4–2's initial current spike. This application note will give a basic introduction to TLP measurements and explain the datasheet parameters extracted from TLP for SDI Technology's protection products.



Comparison of a Current Waveform of IEC 61000-4-2 with TLP Pulses at 8 and 16 A.

The IEC 61000-4-2 ESD waveforms is true to the Standard and is shown here as captured on an oscilloscope. The points A, B, and C show the points on the waveforms specified in IEC 61000-4-2.

Transmission Line Pulse (TLP) Version.

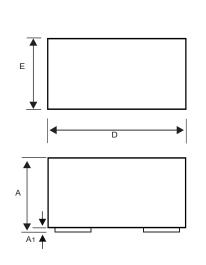




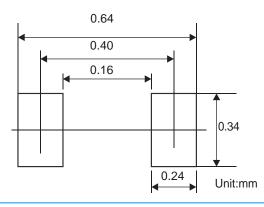
0201/DFN0603

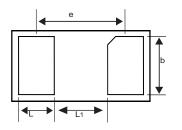
## ESD3.3V02D-ULC

## 0201/DFN0603 Package Outline & Dimensions



#### Suggested PAD Layout





Symbol	Millimeters			
Symbol	Min	Nom	Max	
Α	0.270	0.300	0.340	
A1	0	0.020	0.050	
D	0.550	0.600	0.650	
E	0.250	0.300	0.350	
е	0.340REF			
L	0.140	0.180	0.240	
b	0.200	0.250	0.300	
L1	0.150REF			

#### **Ordering Information**

Device	Device Marking		Package Quantity	
ESD3.3V02D-ULC	3L	0201/DFN0603	10,000pcs/Reel	7 inch